Reconsideration of the rejection of claims 18-22 under 35 U.S.C. 112, second paragraph, as being indefinite is respectfully requested for the following reasons.

Claim 18 is generalized to claim a single level of integration or multilevels of integration, if required to complete the circuit. For example, if additional patterned conducting layers are not required to complete the integration, then the structure shown in Fig. 7 is claimed in claim 18. If two additional layers of integration are required, then Fig. 8 is the structure claimed. Please read the second paragraph on page 18 of the specification to understand the claim. The claim is written to cover one or more levels of integration as needed to complete the integrated circuit.

Reconsideration of the rejection of claims 18-20, 22 under 35 U.S.C. 103(a) as being unpatentable over Lou (U.S. Patent No. 5,759,906) is respectfully requested for the following reasons.

The applicant's invention is a method and structure for avoiding non-uniform polish-back in the kerf area between chips. The Lou reference cited by the Examiner is for planarizing the insulating layers over the required metal wiring needed to sire up the integrated circuits on the individual chip areas. Lou is completely silent on designing additional patterned layers in the kerf area to avoid non-uniform polish-back at the edge of the chips and

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between the chips. The applicant's invention, therefore, is non-obvious and patentable over Lou.

The prior art made of record but not relied upon was reviewed and was found to be not relevant to the applicant's invention.

Dependent claims 19-22, do not stand on their own merits but support the independent claim 18.

It is requested that Examiner Jose R. Diaz call the undersigned Attorney at 845-452-5863 should there be anything that can be done to help bring this Patent Application to Allowance.

Respectfully submitted,

Stephen B. Ackerman

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